



Estimating Space ASICs Using SEER-IC/H

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Today's Topics



- Why Estimate ASICs
- ASIC Basics
- Our Estimating Challenge
- Summary



Why Estimate ASICs?



- ASIC devices are found in many of today's advanced electronics and high performance military designs
- There are various types of ASIC technologies each with advantages specific to the application
- Standard cell ASICs provide critical high performance specialized functionality typically not offered by other types of micro-electronics technologies (FPGAs, Structured Cells, etc.)
- Advancements in ASIC technology are driving development cost for advanced ASICs
- Parametric modeling may provide a viable solution for micro-electronic development and production cost estimation



ASIC Basics



- Application Specific Integrated Circuit
 - Custom designed for a specific application
 - Multilayered integrated circuit design
 - Hardwired to allow for high speed operation
 - Overall increased computational capacity over non-ASIC devices
- Varieties of ASICs
 - Full Custom
 - Standard Cell
 - Structured Cell
 - Gate Array
- ASIC Design Cost Drivers
 - Technology node
 - Die Size
 - Number of Gates (total gates vs. logic gates)
 - I/O Pinouts
 - Packaging



G A L O R A T H



The ASIC Solution



- ASIC Characteristics
 - Favorable Size, Weight and Power Characteristics
 - High speed operating capability
 - Overall increased computational capacity
- ASIC Applications
 - Commercial market has driven widespread use of ASIC devices in various applications (Wireless devices, PDAs, Gaming Platforms)
 - Military electronics have been adapting ASIC devices into their design applications to increase performance in challenging environments

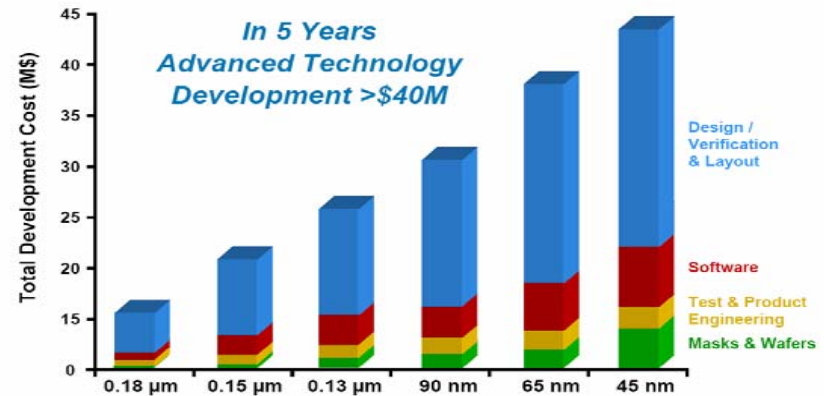




Micro-Electronic Development Cost Trends



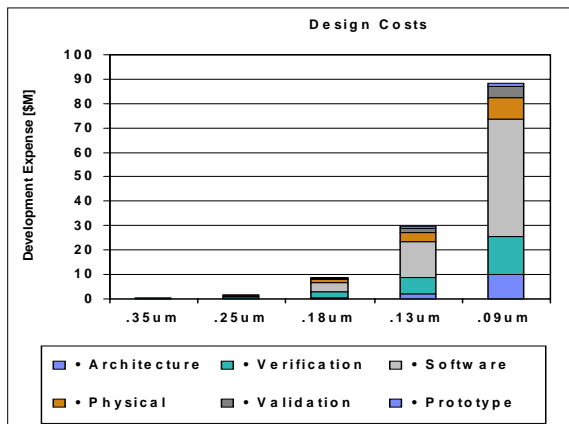
Increasing Development Cost



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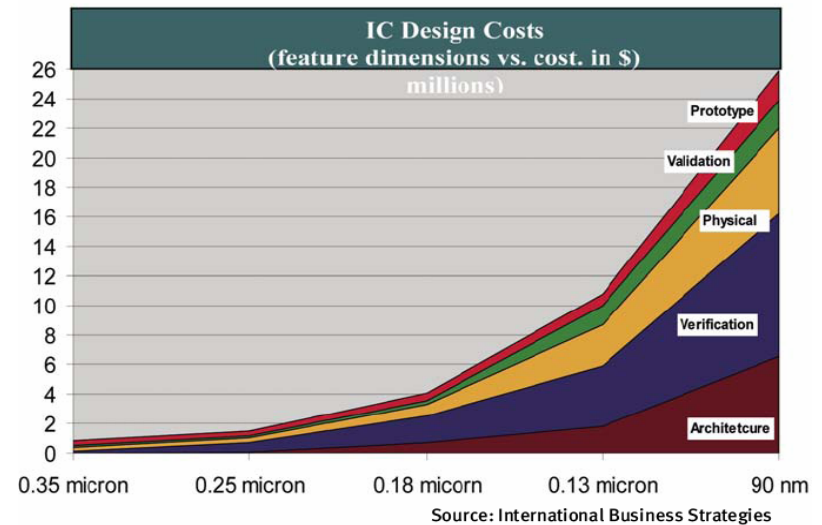


...But wait, there's more...Complexity and Cost



Source: IBS, Inc.

ASIC Product Mktg | IBM Confidential | © 2004 IBM Corporation



Source: International Business Strategies



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Our Estimating Challenge



- Estimating ASIC Devices by Analogy
 - Not applicable/conducive to CER development
 - Historical data not readily available
 - Detailed design knowledge necessary
 - Limited space applications
- Parametric Cost Modeling of ASIC Devices
 - Knowledge Bases provide a reasonable starting point when not all design parameters are known
 - Ability to customize knowledge bases
 - Ability to calibrate against existing knowledge bases
 - Establishes a framework for future improvements and updates



Our Approach Using SEER-IC



- SEER-IC Cost Model Assessment
 - ASIC data request to MILSATCOM contractors
 - Extensive interviews with space vehicle contractors to collect the required ASIC technical parameters and associated cost data
 - Modeled 24 space ASIC devices in SEER-IC for comparison with actual development cost data
 - Reviewed both the quantitative technical parameters and qualitative assessment settings with contractors for the ASICs modeled
 - Emphasis on capturing the technical aspects of each ASIC device in SEER-IC model
 - Final Modeling Adjustments



ASIC Modeling in SEER-IC



PRODUCT DESCRIPTION

- Chip Area (sq mm)	100.00	100.00	100.00
- Feature Size (micron)	0.09	0.09	0.09
- Transistors Per Chip	0	0	0
- Gates Per Chip	1,000,000	2,000,000	3,000,000
- Input/Output Pins Per Chip	100	100	100
- Process Type		CMOS	
- Package Type		Ball Grid	
- Wafer Diameter (mm)	200.00	200.00	200.00
- Operating Frequency	Low	Low	Low

Technical Quantitative Parameters

MISSION DESCRIPTION

- Chip Classification		Custom	
- Operating Environment		Military	

PROGRAM DESCRIPTION

- New Design	50.00%	50.00%	50.00%
- Iterations	1	1	1
- Certification Level	Nom+	Nom+	Nom+

DEVELOPMENT ENVIRONMENT

- Developer Capability & Experience	Nom	Nom+	Hi-
- Development Tools & Practices	VHi-	VHi	VHi
- Requirements Volatility	Low	Low	Low+

Qualitative Parameters

PRODUCTION ENVIRONMENT

- Production Experience	Nom	Nom+	Hi-
- Production Tools & Practices	Nom	Nom+	Hi-

PROGRAM SCHEDULE

- Start Date for Development		1/01/04	
- Prototype Quantity		22	
- Start Date for Production		1/01/05	
- Optional Specified Yield		80.00%	

PRODUCTION

- Prior Production Units	0	0	0
- Total Production Quantity		2,000	
- Percentage of Item Purchased		0.01%	
- Production Unit Purchase Cost		0.00	
PROBABILITY		50.00%	

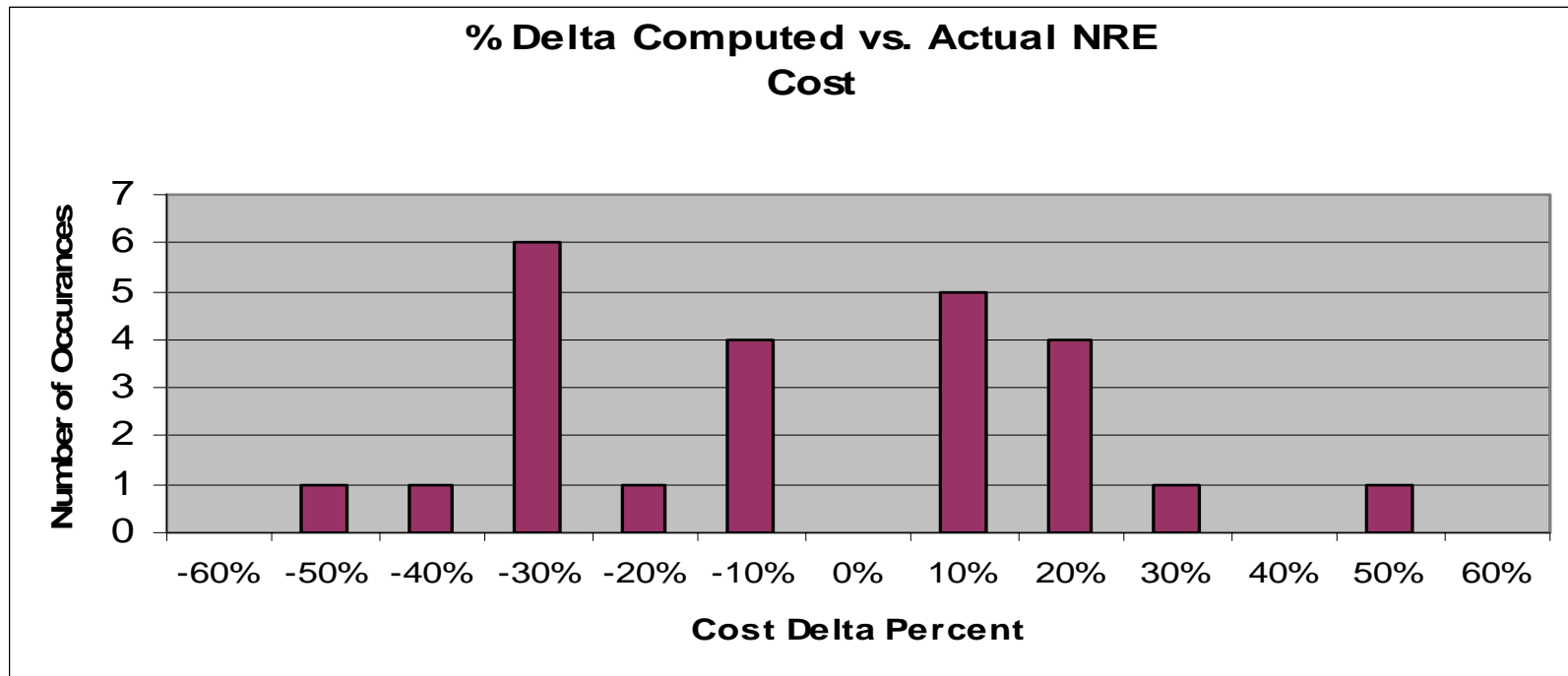
ECONOMIC FACTORS

- Development Cost Wraps/Fee		0.00%	
- Production Cost Wraps/Fee		0.00%	



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ASIC Cost Modeling Comparison



- Initial Comparison Between Modeled and Actual Cost
 - Individual errors on modeled ASIC devices were significant
 - Ensemble error on modeled ASICs were reasonable



Post SEER-IC Adjustments



- ASIC Cost Modeling Comparison
 - Reviewed outlier points to distinguish complexity
 - Error in cost data provided by contractors
 - Individual ASIC complexity is lost in grouped actual cost data provided by contractors
- Post SEER-IC Calibration Adjustments
 - Applied an adjustment factor to each of the individually modeled ASIC devices to minimize ensemble error
 - Adjustment factor is only applicable to these specific data, not one size fits all



Summary



- ASIC technology is becoming more prevalent in Military electronics applications with standard cell ASICs leading the other ASIC types in popularity
- ASIC development costs are continuing to increase and need to be estimated separately from electronic board cost estimation
- Parametric cost modeling of ASIC devices provide a viable method of estimating the development cost of these devices provided research continues on advancements in the industry and the models are updated regularly



Future Related Topics



- Advanced Technology Node Calibration Studies
 - Calibration of SEER-IC/H at advanced technology nodes
- Other Micro-Electronic Applications
 - Field Programmable Gate Arrays (FPGAs)
 - Multi-Chip Module (MCM) technologies
 - System On a Chip (SOC) technologies
- Model Comparison Between SEER-IC and SEER-H
 - Compare the enhanced modeling capability of SEER-H (IC module) with the previous SEER-IC model